

Product Bulletin

Document #:PB23331X Issue Date:18 May 2020

Title of Change:	AR0261 Mono Datasheet		
Effective date:	18 May 2020		
Contact information:	Contact your local ON Semiconductor Sales Office or Sonya. Yip@onsemi.com		
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.		
Change Category:	Documentation Change		
Change Sub-Category(s):	Datasheet/Product Doc change		
Sites Affected:			
ON Semiconductor Sites		External Foundry/Subcon Sites	

None

Description and Purpose:

The AR0261 Mono datasheet has been updated. These changes do not affect form, fit, or function of the product.

AR0261 Mono Datasheet Changes:

1. Updated responsivity in "Table 1, Key Performance Parameters"

Old Table 1:

None

Table 1. KEY PERFORMANCE PARAMETERS

Parameter		Value	
Optical Format		1/6-inch (16:9)	
Active Pixels		1936 (H) x 1096 (V)	
Pixel Size		1.4 µm Back Side Illuminated (BSI)	
Die Size Input Clock Frequency		4.09 mm x 3.89 mm (15.91 mm ²)	
		10-48 MHz	
Interface		Maximum PHY MIPI Data Output Rate per Lane: • 1 Gbps for MIPI 1st data lane (lane 0) when operating on one MIPI lane • 758 Mbps for both MIPI 1st data lane (lane 0) and 2nd data lane (lane 1) when operating on two MIPI lanes	
ADC Reso	lution	10 bits, on-die	
Analog Ga	in	1x, 2x, 4x, 8x	
Compression 3D Support Supply VAA, Voltage VAA_PIX		DPCM: 10-8-10, 10-6-10	
		Frame rate and exposure synchronization; color stats and color gains	
		2.6-2.9 V (2.8 V Nominal)	
	VDD_IO	1.7-1.9 V (1.8 V Nominal)	
	VDD	1.14-1.3 V (1.2 V Nominal)	
	VDD_PHY	1.14-1.3 V (1.2 V Nominal)	
Power Cor	sumption	175 mW at 2 Mp 60 fps (+70°C) Typical	
Responsivity SNHMAX Dynamic Range Operating Temperature		0.75 V/lux-sec	
		37.5 db (Esumated)	
		66.5 dB (Estimated)	
		-30°C to +70°C	

New Table 1:

Table 1. KEY PERFORMANCE PARAMETERS

Parameter		Value				
Optical Format		1/6-inch (16:9)				
Active Pixels Pixel Size Die Size Input Clock Frequency		1936 (H) x 1096 (V) 1.4 μm Back Side Illuminated (BSI) 4.09 mm x 3.89 mm (15.91 mm²) 10–48 MHz				
				Interface		Maximum PHY MIPI Data Output Rate per Lane: • 1 Gbps for MIPI 1st data lane (lane 0) when operating on one MIPI lane • 758 Mbps for both MIPI 1st data lane (lane 0) and 2nd data lane (lane 1) when operating on two MIPI lanes
				ADC Reso	lution	10 bits, on-die
				Analog Gain Compression 3D Support		1x, 2x, 4x, 8x
DPCM: 10-8-10, 10-6-10						
Frame rate and exposure synchronization; color stats and color gains						
Supply Voltage	VAA, VAA_PIX	2.6-2.9 V (2.8 V Nominal)				
	V00_I0	1.7-1.9 V (1.8 V Nominal)				
	VDD	1.14-1.3 V (1.2 V Nominal)				
	Voo_PHY	1.14-1.3 V (1.2 V Nominal)				
Power Consumption Responsivity SNRMAX		175 mW at 2 Mp 60 fps (+70°C) Typical				
		14.2 ke-/lux*s (6,500K, 670 nm IR-cut filter)				
		37.5 dB (Estimated)				
Dynamic Range		66.5 dB (Estimated)				
Operating	Temperature	-30°C to +70°C				

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2. Updated "Table 3, Available Part Numbers"

Old Table 3:

ORDERING INFORMATION

Table 3. AVAILABLE PART NUMBERS

Part Number	Description	
AR0261CSSM00SMD20	Bare Die, Monochrome	
AR0261CSSM00SMKA0-CR-E	Chip Scale Package (CSP), Monochrome Engineering Sample	
AR0261CSSM00SMKAH3-GEVB	Chip Scale Package (CSP), Monochrome Evaluation Headboard	

See the ON Semiconductor Device Nomenclature document (<u>TND310/D</u>) for a full description of the naming convention used for image sensors. For reference documentation, including information on evaluation kits, please visit our web site at www.onsemi.com.

New Table 3:

ORDERING INFORMATION

Table 3. AVAILABLE PART NUMBERS

	Part Number	Description	
	AR0261CSSM00SMD20	Bare Die, Monochrome	
C	AR0261CSSM00SMKA0-CP-E	Chip Scale Package (CSP)with Protective Film, Monochrome Engi- neering Sample	
AR02	AR0261CSSM00SMKAH3-GEVB	Chip Scale Package (CSP with Protective Film), Monochrome Evaluation Headboard	
	AR0261CSSM00SMKA0-CR-E	Chip Scale Package (CSP) without Protective Film, Monochrome Engineering Sample	

See the ON Semiconductor Device Nomenclature document (TND310/D) for a full description of the naming convention used for image sensors. For reference documentation, including information on evaluation kits, please visit our web site at www.onsemi.com.

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

AR0261CSSM00SMD20	AR0261CSSM00SMKA0-CP-E	

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